

In the Claims

1 (Original). A method comprising:

forming a curved microspring spaced over a semiconductor structure; and

forming a spring arm on said semiconductor structure over said microspring.

2 (Original). The method of claim 1 including forming a curved microspring by depositing a first material on said structure, covering said first material with a conductive second material and subsequently removing said first material.

3 (Original). The method of claim 2 including removing the first material by heating the first material.

4 (Original). The method of claim 1 including forming said microspring, an actuator for said spring arm, and at least a portion of said spring arm by forming a first layer on said semiconductor structure and patterning said first layer.

5 (Original). The method of claim 4 including covering said layer with a removable material and covering said removable material with a second layer.

6 (Original). The method of claim 5 including removing said removable material.

7 (Original). The method of claim 6 including heating said material to remove said material.

8 (Original). The method of claim 7 including removing the first material underneath the microspring and said removable material at the same time.

9 (Original). The method of claim 1 including forming said microspring of a plurality of strips.

10 (Original). The method of claim 9 including forming said strips under a free end of said spring arm.

Claims 11-19 (Canceled).

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20 (Original). A microelectromechanical system structure comprising:

a semiconductor structure;

a removable material on said semiconductor structure;

a curved microspring formed over said removable material; and

a spring arm formed on said semiconductor structure over said microspring.

21 (Original). The structure of claim 20 including a removable material between said spring arm and said microspring.

22 (Original). The structure of claim 21 wherein said removable material is removable through the application of heat.

23 (Original). The structure of claim 20 including an actuator formed on said semiconductor structure to move said spring arm towards and away from said microspring.

24 (Original). The structure of claim 21 wherein said spring arm includes a pair of opposed ends, said microspring is attached to said semiconductor structure on one end and is arranged above the microspring on the other end.

25 (Original). The structure of claim 21 wherein said microspring is formed of a plurality of spaced, curved strips.

26 (Original). The structure of claim 25 wherein each of said strips includes two different layers of material.

27 (Original). The structure of claim 26 wherein one of said layers is a resilient conductor.

28 (Original). The structure of claim 20 wherein said removable material is organic.

29 (Original). The structure of claim 28 wherein said removable material is polymeric.

30 (Original). The structure of claim 21 wherein said removable material under said microspring and said removable material under said spring arm is the same material, said material being removable upon heating.